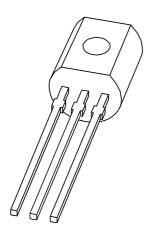
DISCRETE SEMICONDUCTORS

DATA SHEET



BC546; BC547 NPN general purpose transistors

Product specification Supersedes data of 1999 Apr 15

2004 Nov 25





NPN general purpose transistors

BC546; BC547

FEATURES

- Low current (max. 100 mA)
- Low voltage (max. 65 V).

APPLICATIONS

• General purpose switching and amplification.

DESCRIPTION

NPN transistor in a TO-92; SOT54 plastic package. PNP complements: BC556 and BC557.

PINNING

PIN	DESCRIPTION
1	emitter
2	base
3	collector

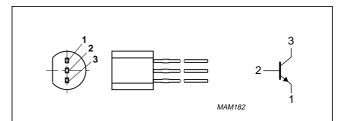


Fig.1 Simplified outline (TO-92; SOT54) and symbol.

ORDERING INFORMATION

TYPE NUMBER		PACKAGE	
TIPE NUMBER	NAME	DESCRIPTION	VERSION
BC546A	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54
BC546B			
BC547			
BC547B			
BC547C			

NPN general purpose transistors

BC546; BC547

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter			
	BC546A; BC546B		_	80	V
	BC547		_	50	V
V _{CEO}	collector-emitter voltage	open base			
	BC546A; BC546B		_	65	V
	BC547; BC547B; BC547C		_	45	V
V _{EBO}	emitter-base voltage	open collector			
	BC546A; BC546B		_	6	V
	BC547; BC547B; BC547C		_	6	V
I _C	collector current (DC)		_	100	mA
I _{CM}	peak collector current		_	200	mA
I _{BM}	peak base current		_	200	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	500	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	ambient temperature		-65	+150	°C

Note

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	250	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

^{1.} Transistor mounted on an FR4 printed-circuit board.

NPN general purpose transistors

BC546; BC547

CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

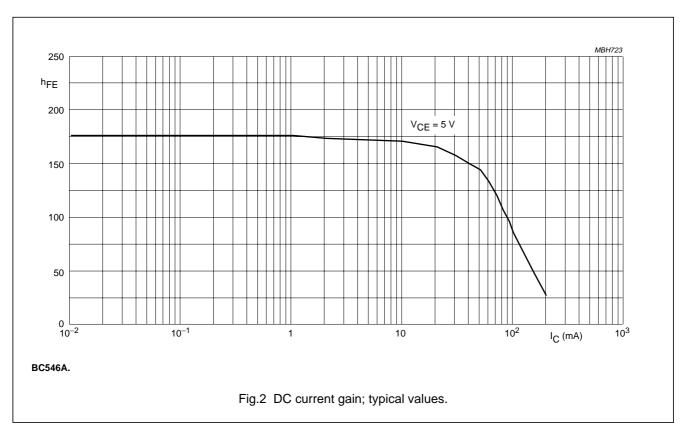
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	V _{CB} = 30 V; I _E = 0 A	_	_	15	nA
		V _{CB} = 30 V; I _E = 0 A; T _j = 150 °C	_	_	5	μΑ
I _{EBO}	emitter-base cut-off current	V _{EB} = 5 V; I _C = 0 A	_	_	100	nA
h _{FE}	DC current gain BC546A	$V_{CE} = 5 \text{ V; } I_{C} = 10 \mu\text{A;}$ see Figs 2, 3 and 4	_	90	_	
	BC546B; BC547B BC547C		_	150 270	_	
	DC current gain BC546A BC546B; BC547B BC547C BC547	$V_{CE} = 5 \text{ V}$; $I_{C} = 2 \text{ mA}$; see Figs 2, 3 and 4	110 200 420 110	180 290 520	220 450 800 800	
V _{CEsat}	collector-emitter saturation	I _C = 10 mA; I _B = 0.5 mA	-	90	250	mV
	voltage	$I_C = 100 \text{ mA}; I_B = 5 \text{ mA}$	_	200	600	mV
V_{BEsat}	base-emitter saturation voltage	$I_C = 10 \text{ mA}; I_B = 0.5 \text{ mA}; \text{ note 1}$	_	700	_	mV
		$I_C = 100 \text{ mA}; I_B = 5 \text{ mA}; \text{ note 1}$	_	900	-	mV
V_{BE}	base-emitter voltage	$V_{CE} = 5 \text{ V}; I_{C} = 2 \text{ mA}; \text{ note } 2$	580	660	700	mV
		$V_{CE} = 5 \text{ V}; I_{C} = 10 \text{ mA}$	_	_	770	mV
C _c	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = i_e = 0 \text{ A}; f = 1 \text{ MHz}$	_	1.5	_	pF
C _e	emitter capacitance	$V_{EB} = 0.5 \text{ V}; I_C = I_c = 0 \text{ A};$ f = 1 MHz	_	11	_	pF
f _T	transition frequency	V _{CE} = 5 V; I _C = 10mA; f = 100 MHz	100	_	_	MHz
F	noise figure	$V_{CE} = 5 \text{ V; } I_{C} = 200 \mu\text{A; } R_{S} = 2 k\Omega;$ $f = 1 \text{ kHz; } B = 200 \text{ Hz}$	_	2	10	dB

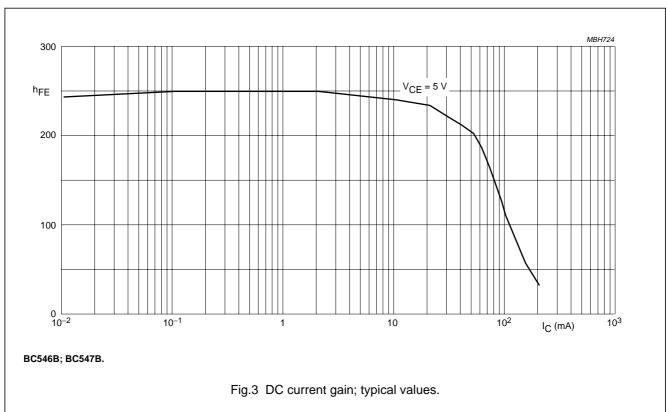
Notes

- 1. V_{BEsat} decreases by about 1.7 mV/K with increasing temperature.
- 2. V_{BE} decreases by about 2 mV/K with increasing temperature.

NPN general purpose transistors

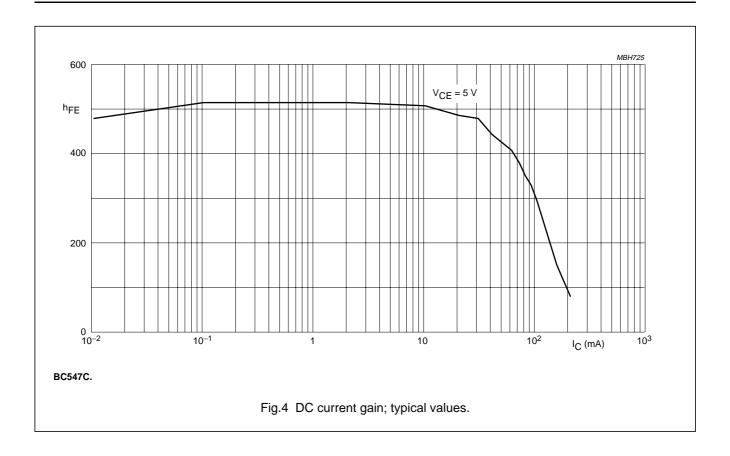
BC546; BC547





NPN general purpose transistors

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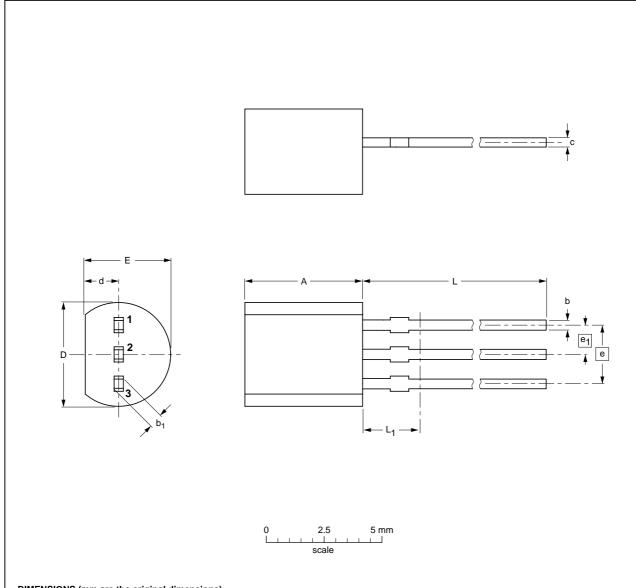
NPN general purpose transistors

BC546; BC547

PACKAGE OUTLINE

Plastic single-ended leaded (through hole) package; 3 leads

SOT54



DIMENSIONS (mm are the original dimensions)

UNIT	A	b	b ₁	С	D	d	E	е	e ₁	L	L ₁ ⁽¹⁾ max.	
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5	

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE	
SOT54		TO-92	SC-43A		-04-06-28 04-11-16	

NPN general purpose transistors

BC546; BC547

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Notes

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